

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 19 February 2026, 15:05 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.29%	SILVER, ELEMENTAL	7440-22-4	3.87%
			Elemental silicon	7440-21-3	96.13%
Die attach	Other nonferrous metals	3.26%	Phenol, polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6	3%
			4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	22%
			SILVER, ELEMENTAL	7440-22-4	75%
Encapsulation	EP (Epoxy resin)	56.8%	Carbon black	1333-86-4	1%
			Phenol, polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6	7%
			4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	11%
			Silicon dioxide	60676-86-0	81%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.76%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	3.19%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	32.7%	Elemental iron	7439-89-6	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-323F_(DJ)_ Pb&H-free	Diode SMD	0.004074	g

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